

In the Specification:

Please amend the specification as follows:

Page 18, 2nd full paragraph.

A1
As shown in FIG. 4 schematically, leadframe 401 comprises base 406 made of copper or copper alloy. On the surface of this copper is a sequence of layers, described in detail in FIG. 2. Closest to the copper is a first layer 407 of nickel. This layer is actually a stack of layers, followed by spot-plated layers 408 and 409 of palladium. Palladium layer 409 is incorporated into the meniscus of the bulk solder 410 in the process of surface-mounting device 400 onto a substrate or board 420.

In the Claims:

Please amend the claims as follows:

A2
7. (amended) The leadframe according to Claim 1 wherein said film of palladium is sufficiently thin that the surface of said leadframe not covered by said layer of palladium comprises nickel and nickel oxide as well as palladium.

17-20. (cancelled)

Please add the following new claims.

A3
21. (new) A semiconductor device, comprising:

a leadframe, comprising:

a first layer of noble metal covering said leadframe;

a second layer of said noble metal covering portions said first layer

of said noble metal, wherein said first layer of said noble metal is thinner than said second layer of said noble metal.

22. (new) The semiconductor device of Claim 21, wherein said noble metal is palladium.